

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	0	(epoxy same (solder near powder) same ((flux or fluxing) near agent)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 08:14
S2	1	(epoxy same (solder near powder)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:33
S3	84	epoxy same (solder near powder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 08:21
S5	538	(adhesive or resin or glue) same (solder near powder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:39
S6	15	S5 and (heat near sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 16:02
S7	61	transient near liquid near phase near sintering	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 16:02
S9	64	("3915729" "4391742" "4619715" "4789411" "4859268" "5062896" "5064482" "5088189" "5128746" "5150195" "5156771" "5204025" "5328522" "5334261" "5346558" "5376403" "5382300" "5404044" "5450290" "5640761" "5641996" "5714803" "5744285" "5783867" "5822856" "5844320" "5851311" "5985043" "6054761" "6281040" "6579474").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 08:14

S10	181406	(heat near (dissipate or dissipating or dissipation)) or (heat near spreader) or (heat near sink) or (heat near fin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 08:19
S11	5	S9 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 08:19
S12	84	(epoxy or epoxies) same (solder near powder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 08:21
S13	3	S10 and S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 08:23
S14	15	S10 same (solder near powder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 08:23
S15	15	("4606962" "4612601" "4711813" "4869954" "4914551" "5062896" "5213715" "5290904" "5328087" "6059952" "6114413" "6207300" "6340113" "6365973" "6451422").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/25 09:44
S16	1147	thermal near interface near material	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:32
S21	15	S16 and ((flux or fluxing) same (polymer or resin or rosin or adhesive) same solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 09:54

S22	29	polymer near solder near hybrid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:05
S24	11	S16 and (fluxing near agent)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 11:00
S25	225	S16 and paste	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:32
S26	126	S25 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:33
S28	75	(fluxing near agent) same ((remove or removed or removing) near3 oxide) same (adhesive or resin or polymer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 13:00
S29	17	(fluxing near agent) same ((remove or removed or removing) near3 oxide) same paste	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 13:00
S31	143	S16 near5 thickness	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:10
S48	15	S10 same ((adhesive or paste or resin) near3 (thermal near conductivity) near5 ("W/mK"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:48

S51	0	S10 same ((adhesive or paste or resin) near3 (thermal near conductivity) near5 ("W/m . degree. C"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:39
S52	0	S10 same ((adhesive or paste or resin) near3 (thermal near conductivity) near5 ("W/m.degree. C"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:39
S54	55	S10 and ((adhesive or paste or resin) near3 (thermal near conductivity) near5 ("W/mK"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 14:39
S55	29	(solder near powder) near5 volume	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 15:01